











SNLS475A - FEBRUARY 2016-REVISED MARCH 2016

LMH1219

LMH1219 Low Power 12G UHD Adaptive Cable Equalizer with Integrated Reclocker

Features

- Supports ST-2082-1(12G), ST-2081-1(6G), ST-424(3G), ST-292(HD), and ST-259(SD)
- Supports SFF8431 (SFP+) for SMPTE 2022-5/6
- Compatible with DVB-ASI and AES10 (MADI)
- Integrated Reference-Less Reclocker Locks to SMPTE and 10GbE Rate: 11.88 Gbps, 5.94 Gbps, 2.97 Gbps. 1.485 Gbps. or Divide-by-1.001 Sub-Rates, 270 Mbps and 10.3125 Gbps
- Adaptive Cable Equalizer at Input 0 (IN0)
- Cable Reach (Belden 1694A):
 - 75 m at 11.88 Gbps (4Kp60 UHD)
 - 120 m at 5.94 Gbps (UHD)
 - 200 m at 2.97 Gbps (FHD)
 - 280 m at 1.485 Gbps (HD)
 - 600 m at 270 Mbps (SD)
- Adaptive Board Trace Equalizer at Input 1 (IN1)
- Low Power: 250 mW (Typical)
- Power Saving Mode: 27 mW
- Integrated Input Return Loss Network
- 2:1 Input Mux, 1:2 Fanout Output with De-**Emphasis**
- Supports Signal Splitter Mode (-6 dB Launch Amplitude)
- On-Chip Loop Filter Capacitor and Eye Monitor
- Powers from Single 2.5 V with On-Chip 1.8 V Regulator
- Configurable by Control Pins, SPI, or SMBus Interface
- 4 mm x 4 mm 24-pin QFN Package
- Operating Temperature Range: -40°C to 85°C

Applications

- SMPTE Compatible Serial Digital Interface
- UHDTV/4K/8K/HDTV/SDTV Video
- Broadcast Video Routers, Switchers, Distribution Amplifiers, and Monitors
- Digital Video Processing and Editing
- 10 GbE SDI Media Gateway

3 Description

The LMH1219 is a low-power, dual-input and dualoutput, adaptive equalizer with integrated reclocker. It supports SMPTE video rates up to 11.88 Gbps and 10 GbE video over IP, enabling UHD video for 4K/8K applications. An extended reach adaptive cable equalizer at INO is designed to equalize data transmitted over 75 Ω coaxial cable and operates over a wide range of data rates from 125 Mbps to 11.88 Gbps. An adaptive board trace equalizer at IN1 is SFF-8431 compatible and supports both SMPTE and 10 GbE data rates.

The integrated reclocker attenuates high frequency jitter and provides the best signal integrity. High input jitter tolerance of the reclocker improves timing margin. The reclocker has a built-in loop filter, and operates without the need of a precision input reference clock. A non-disruptive eye monitor allows real time measurement of the serial data to simplify system debug and accelerate board bring-up.

The integrated 2:1 Mux and 1:2 Fanout provide flexibility for multiple video signals. The output drivers offer programmable de-emphasis to compensate board trace losses at its outputs. The integrated return loss network meets stringent SMPTE specifications across all data rates. The typical power consumption of LMH1219 is 250 mW. In the absence of input signal, power is further reduced to 27 mW.

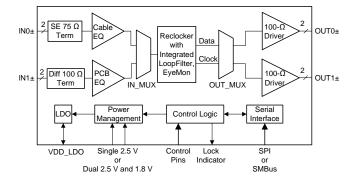
The LMH1219 is pin compatible to LMH1226 (12G UHD reclocker) and LMH0324 (3G adaptive cable equalizer).

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
LMH1219	QFN (24)	4 mm x 4 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Simplified Block Diagram





1	Features 1	5	Device and Documentation Support 3
2	Applications 1		5.1 Community Resources
	Description 1		5.2 Trademarks
	Revision History2		5.3 Electrostatic Discharge Caution
	1.01.01.01.01.01.01.01.01.01.01.01.01.01		5.4 Glossary3

4 Revision History

Cł	hanges from Original (February 2016) to Revision A	Page
•	Product Preview to Production Data Release	1

Product Folder Links: LMH1219



5 Device and Documentation Support

5.1 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E™ Online Community TI's Engineer-to-Engineer (E2E) Community. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

5.2 Trademarks

E2E is a trademark of Texas Instruments.

5.3 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

5.4 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

Product Folder Links: LMH1219



PACKAGE OPTION ADDENDUM

29-Mar-2016

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
LMH1219RTWR	ACTIVE	WQFN	RTW	24	3000	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR	-40 to 85	L1219A2	Samples
LMH1219RTWT	ACTIVE	WQFN	RTW	24	250	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR	-40 to 85	L1219A2	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.



PACKAGE OPTION ADDENDUM

29-Mar-2016

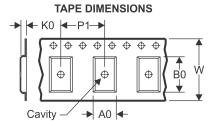
n no event shall TI's liability arising out of	such information exceed the total purchase pr	rice of the TI part(s) at issue in this	document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

www.ti.com 28-Mar-2016

TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

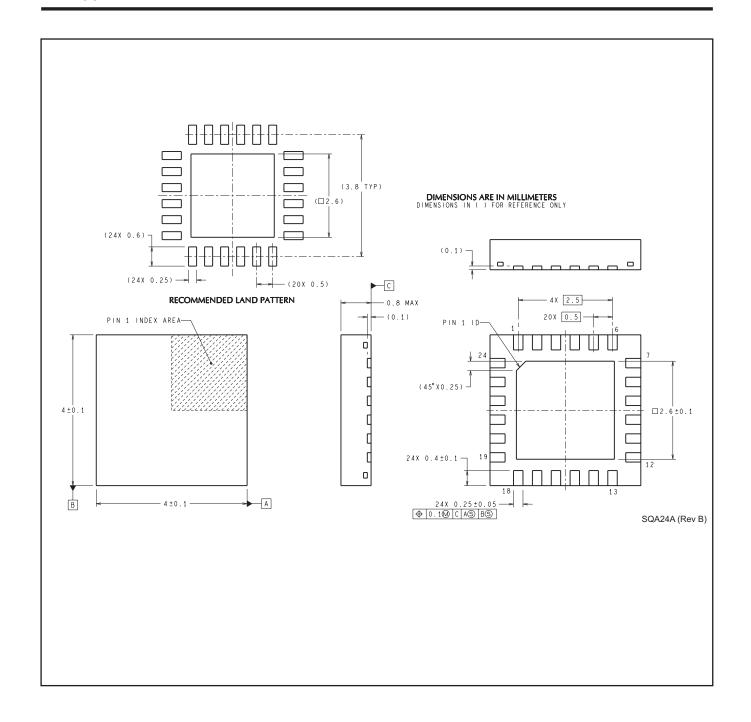
Ī	Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ľ	LMH1219RTWR	WQFN	RTW	24	3000	330.0	12.4	4.3	4.3	1.3	8.0	12.0	Q1
	LMH1219RTWT	WQFN	RTW	24	250	178.0	12.4	4.3	4.3	1.3	8.0	12.0	Q1

www.ti.com 28-Mar-2016



*All dimensions are nominal

	Device	Package Type	Package Type Package Drawing		SPQ	Length (mm)	Width (mm)	Height (mm)	
ı	LMH1219RTWR	WQFN	RTW	24	3000	367.0	367.0	35.0	
	LMH1219RTWT	WQFN	RTW	24	250	213.0	191.0	55.0	



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products Applications

Audio www.ti.com/audio Automotive and Transportation www.ti.com/automotive **Amplifiers** amplifier.ti.com Communications and Telecom www.ti.com/communications **Data Converters** dataconverter.ti.com Computers and Peripherals www.ti.com/computers **DLP® Products** www.dlp.com Consumer Electronics www.ti.com/consumer-apps DSP dsp.ti.com **Energy and Lighting** www.ti.com/energy Clocks and Timers www.ti.com/clocks Industrial www.ti.com/industrial Interface interface.ti.com Medical www.ti.com/medical Logic Security www.ti.com/security logic.ti.com

Power Mgmt power.ti.com Space, Avionics and Defense www.ti.com/space-avionics-defense

Microcontrollers microcontroller.ti.com Video and Imaging www.ti.com/video

RFID www.ti-rfid.com

OMAP Applications Processors www.ti.com/omap TI E2E Community e2e.ti.com

Wireless Connectivity www.ti.com/wirelessconnectivity